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(39) "0104653"
(0) 2003/0104653
(0) 10/82865
(0) 10/829851
(2) 5744827.pn.
(1) 09/944246
(2857) stack$2 adj (package chip)
(2) 5744827.pn.
(0) 09/944246 and 5744827.pn.
(3) 09/944246 5744827.pn.
(1336674) lead
(66066) wire near bond$4
(15744) lead near6 (wire near bond$4)
(53) (stack$2 adj (package chip)) same (lead near6 (wire near bond$4))
(133623) samsung.as.
(41120) cho.in.
(7373) samsung.as. and cho.in.
(1) ((stack$2 adj (package chip)) and (lead near6 (wire near bond$4))) and (samsung.as. and
(20) ((stack$2 adj (package chip)) and (lead near6 (wire near bond$4))) and samsung.as.
(276) (stack$2 adj (package chip)) and (lead near6 (wire near bond$4))
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(stack$2 adj (package chip)) and (lead near6 (wire near bond$4))

Feb. 2004

	U	#	Inventor	Document ID	Issue D	Pg	Title	Current O	Current XRef	Retrieval Cl	$	€	P	¥	£	₹	Image Doc. ID	P
1	☐	☑	Horiuchi, Michio	US 20020031	200203	17	Semiconductor device and process of production of sa	438/125	257/E23.004;		☑	☐	☐	☐	☐	☐	US 20020031	☐
2	☐	☑	Park, Sang Woo	US 6137162 A	200010	12	Chip stack package	257/685	257/686;		☑	☐	☐	☐	☐	☐	US 6137162	☐
3	☐	☐	Ahn, Kie Y. et al.	US 20010033	200110	10	Stacked integrated circuits	365/63			☑	☐	☐	☐	☐	☐	US 20010033	☐
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5	☐	☐	Ahn, Kie Y. et al.	US 6314013 B	200111	11	Stacked integrated circuits	365/63	257/737;		☑	☐	☐	☐	☐	☐	US 6314013	☐
6	☐	☐	Ahn, Kie Y. et al.	US 6122187 A	200009	11	Stacked integrated circuits	365/63	257/673;		☑	☐	☐	☐	☐	☐	US 6122187	☐
7	☐	☐	Ahn, Sang-Ho et	US 20020121	200209	24	Ultra-thin semiconductor package device and method f	257/666	257/678;		☑	☐	☐	☐	☐	☐	US 20020121	☐
8	☐	☐	Akasaki, Hidehik	US 5861670 A	199901	11	Semiconductor device package	257/737	257/700;		☑	☐	☐	☐	☐	☐	US 5861670	☐

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